Applicable customer specifications take precedence over this procedure (reference customer drawing).

<table>
<thead>
<tr>
<th>Description / Dimensions</th>
<th>Picture / Detail</th>
<th>Sample Size / Method / Standard</th>
</tr>
</thead>
<tbody>
<tr>
<td>1) <strong>Inspection for Chips</strong> (Material broken off an edge or a corner):</td>
<td><img src="image1.png" alt="Chip Image" /></td>
<td><strong>Method</strong>: Visual using a 4X illuminated magnification or greater. <strong>Sample Size</strong>: Refer to appropriate flow chart in TT-PC-0186 for inspection level.</td>
</tr>
<tr>
<td>No more than 3 chips per part.</td>
<td><img src="image2.png" alt="Chip Image" /></td>
<td></td>
</tr>
<tr>
<td>Any chip under .020” is not recognized.</td>
<td></td>
<td></td>
</tr>
<tr>
<td>The depth of the chip cannot exceed ½ of the parts thickness.</td>
<td></td>
<td></td>
</tr>
<tr>
<td><strong>Part Size – 1.00” and under</strong></td>
<td></td>
<td></td>
</tr>
<tr>
<td>No single edge chip ≥ .075” in length and width.</td>
<td></td>
<td></td>
</tr>
<tr>
<td><strong>Part Size – Over 1.00”</strong></td>
<td></td>
<td></td>
</tr>
<tr>
<td>No single edge chip ≥ .100” in length and width.</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

2) **Inspection for Holes** (A pit on the surface of the part): | ![Hole Image](image3.png) | **Method**: Visual using a 4X illuminated magnification or greater. **Sample Size**: Refer to appropriate flow chart in TT-PC-0186 for inspection level. |
| No more than 2 holes per part | ![Hole Image](image4.png) | |
| **Part Size – 1.00” and under** |  |
| No hole to exceed .030”. |  |
| **Part Size – Over 1.00”** |  |
| No hole to exceed .040”. |  |
3) **Inspection for Air-gaps and Glue-gaps** (A gap between the assembly):

Air gaps are acceptable if they do not exceed 40% of the ferrite circumference.

**Method:** Visual using a 4X illuminated magnification or greater.

**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.

<table>
<thead>
<tr>
<th>4) <strong>Inspection for Cracks and Laminations:</strong></th>
</tr>
</thead>
<tbody>
<tr>
<td>None allowed</td>
</tr>
</tbody>
</table>

**Method:** Visual using a 4X illuminated magnification or greater.

**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.
### 5) Inspection for Material Imperfections (Kiln Reaction, Large Grains, Contamination):

- **None allowed**

Not Acceptable

| Method: Visual using a 4X illuminated magnification or greater. |
| Sample Size: Refer to appropriate flow chart in TT-PC-0186 for inspection level. |

**Minor scratches are Acceptable**

- At low magnification
- At high magnification

### 6) Inspection for Blemishes (A discoloration in the material):

- **No more than 3 blemishes per part**
  - **Part Size – 1.00” and under**
    - No blemish to exceed .030”.
  - **Part Size – Over 1.00”**
    - No blemish to exceed .040”
  - No blemishes allow if they create a hole.

Method: Visual using a 4X illuminated magnification or greater.

Sample Size: Refer to appropriate flow chart in TT-PC-0186 for inspection level.
### 7) Inspection for Gaps:

**Gaps:** are acceptable as long as there is no “Short Circuit” *(see NonMetalized Side).* When Gaps are detected, Visual Inspection shall be performed on the non-metalized side for any silver spots or trace through the Gap that create “Short Circuit”.

**Short Circuit:** Silver spots or trace on the non-metallized side at the interface area of the Dielectric Ring and Magnetic Disk.

**Method:** Visual using a 4X illuminated magnification or greater.

**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.

### 8) Inspection for Voids (a hole) and Divots (a dent) in the metallization surface.

**For Voids:**
No voids $\geq .040”$
No more than 5 voids per part.

**Method:** Visual using a 4X illuminated magnification or greater.

**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.

**For Divots:**
No divot $\geq .100”$
No more than 5 divots per part.

**Method:** Visual using a 4X illuminated magnification or greater.

**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.

**Note:** No more than 5 of each defect allowed per part
### 9) Inspection for Excess metal on non-metalized surface:

No metal > 0.025” in greatest dimension allowed.

**Method:** Visual using a 4X illuminated magnification or greater.

**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.

### 10) Inspection of excess metal on the O.D./edge:

a. No bridging allowed between top and bottom surfaces

b. Parts are allowed to have excess metal on 1/3 of the thickness.

c. Metal specks not allowed below 2/3 of the part thickness as measure from the metalized side.

**Method:** Visual using a 4X illuminated magnification or greater.

**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.

### 11) Inspection for Pull-back (the ceramic gap between the edge of the part and where the metal begins on the metalized surface):

**All Part Sizes**

The pull back can not be >0.015”

**Method:** Visual using a 4X illuminated magnification or greater.

**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.

### 12) Inspection for visual imperfections on the metallized surface:

- No surface imperfections, blisters, debris, excess metal etc. > 0.040” in greatest dimension

- No discernable surface condition that alters the surface uniformity by producing visible peaks and build-up

**Method:** Visual using a 4X illuminated magnification or greater.

**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.